

Process Change Notice

Parts Affected:

Chip processes CP192V(NPN) and CP592V(PNP), small signal discrete semiconductors, wafers, and die in chip form.

Extent of Change:

An overall reduction of the die area.

The CP192V chip process currently measures 13 x 17 mils and is being replaced by the CP392V chip process which measures 11 x 11 mils.

The CP592V chip process currently measures 12 x 20 mils and is being replaced by the CP792V chip process which measures 11 x 11 mils.

Reason for Change:

To accommodate assemblies of extremely small surface mount, epoxy molded packages.

Effect of Change:

This change does not affect the electrical characteristics of any device.

Effective Date of Change:

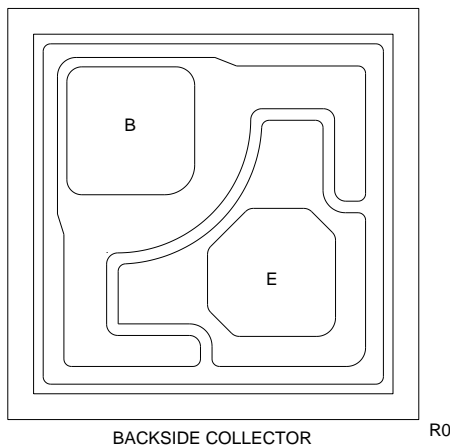
Existing inventory will be shipped until depleted.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Figures:

CP392V / CP792V Chip Geometry



Die Size: 11 x 11 mils
Die Thickness: 7.1 mils
Bond Pad Area (Base): 3.7 x 3.7 mils
Bond Pad Area (Emitter): 3.7 x 3.7 mils

PCN # 107

Notification Date:

29 June 2006

Part Numbers Affected:

2N3904
CMPT3904
CMST3904
CMUT3904
CMXT3904
CMXT3946
CXT3904
CZT3904
MMPQ3904
MMPQ6700
MPQ3904
MPQ6700
CP192V-2N3904-WN
CP192-CMPT3904-CT
CP192-CMPT3904-WN

2N3906
CMPT3906
CMPT3906E
CMST3906
CMUT3906
CMXT3906
CMXT3946
CXT3906
CZT3906
MMPQ3906
MMPQ6700
MPQ3906
MPQ6700
2N3251
CP592-CEN1085-CT
CP592-CEN1085-WN
CP592-CMPT3906-CT
CP592-CMPT3906-WN
CP592-2N3251-CT
CP592-2N3906-WN